



AF/2800

PATENT
Attorney Docket No.: SAM-0313

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE.

#2/B(NE)
6/6/03
Purles

Applicant(s): Soo-geun Lee, *et al.*

Examiner: Nguyen, H.

Serial No.: 10/081,661

Group Art Unit: 2812

Filing Date: February 22, 2002

Title: METHOD OF MANUFACTURING INTERCONNECTION LINE IN SEMICONDUCTOR DEVICE

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

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AMENDMENT AFTER FINAL REJECTION

Sir:

This is in response to the final Office Action mailed on March 6, 2003. It is requested that the following amendments be entered and that the following remarks be considered.

Please amend the application as follows:

In the Claims

Please amend the claims as follows:

1. (Amended) A method of forming an interconnection line in a semiconductor device comprising:

forming a first etching stopper on a lower conductive layer which is formed on a semiconductor substrate;

forming a first interlayer insulating layer on the first etching stopper;

forming a second etching stopper on the first interlayer insulating layer;

forming a second interlayer insulating layer on the second etching stopper;

Do not enter
in 6-16-03

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